

Appl. No. 10/064,462  
Amdt. dated March 30, 2005  
Reply to Office action of December 01, 2004

# AMENDMENTS TO THE CLAIMS

1. (currently amended) A method for attaching ~~[[a]]~~ an  
integrated circuit (IC) package to a circuit board, the  
5 IC package having a plurality of electrical contacts,  
the plurality of electrical contacts being disposed on  
a major surface of the IC package in an arrangement having  
a perimeter, the method comprising:

10 positioning the IC package relative to the circuit  
board, such that the major surface of the IC  
package is adjacent to a major surface of the  
circuit board;

15 electrically connecting the IC package to the  
circuit board through the plurality of  
electrical contacts; and  
attaching disposing at least one ~~anchor~~ metal strap  
directly to the IC package to mechanically  
attaching attach the IC package to the circuit  
board;

20 wherein the ~~anchor~~ metal strap does not provide an  
electrical contact between the IC package and the  
circuit board.

25 2. (currently amended) The method of claim 1 wherein the  
~~anchor~~ metal strap is disposed at a location outside of  
the perimeter of the plurality of electrical contacts.

3. (original) The method of claim 2 wherein the major

Appl. No. 10/064,462  
Amdt. dated March 30, 2005  
Reply to Office action of December 01, 2004

surface of the IC package has a rectangular shape, and the arrangement of the plurality of electrical contacts is a grid-like array.

5 4. (currently amended) The method of claim 3 wherein ~~the anchors~~ metal straps are disposed at four corners of the major ~~[[face]]~~ surface of the IC package.

10 5. (currently amended) The method of claim 3 wherein ~~the anchors~~ metal straps are disposed along four edges of the major ~~[[face]]~~ surface of the IC package.

15 6. (currently amended) The method of claim 3 wherein ~~the anchors~~ metal straps are disposed on edges of the IC package.

7-11. (cancelled)

20 12. (original) The method of claim 1 wherein the electrical contacts are solder balls.

13. (original) The method of claim 1 wherein the electrical contacts are pins.

25 14. (new) A method for attaching an integrated circuit (IC) package to a circuit board, the IC package having a plurality of electrical contacts, the plurality of electrical contacts being disposed on a major surface

Appl. No. 10/064,462  
Amdt. dated March 30, 2005  
Reply to Office action of December 01, 2004

of the IC package in an arrangement having a perimeter,  
the method comprising:

positioning the IC package relative to the circuit  
board, such that the major surface of the IC  
5 package is adjacent to a major surface of the  
circuit board;

electrically connecting the IC package to the  
circuit board through the plurality of  
electrical contacts; and

10 disposing at least one strip of solder between the  
major surface of the IC package and the major  
surface of the circuit board to mechanically  
attach the IC package to the circuit board;

wherein the strip of solder does not provide an  
15 electrical contact between the IC package and the  
circuit board.

15. (new) The method of claim 14 wherein the strip of  
solder is disposed at a location outside of the perimeter  
20 of the plurality of electrical contacts.

16. (new) The method of claim 15 wherein the major surface  
of the IC package has a rectangular shape, and the  
arrangement of the plurality of electrical contacts is  
25 a grid-like array.

17. (new) The method of claim 16 wherein the strip of  
solder is disposed along four edges of the major surface

Appl. No. 10/064,462  
Amdt. dated March 30, 2005  
Reply to Office action of December 01, 2004

of the IC package.